



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0603             |
| L         | 1.6mm +/-0.17mm  |
| W         | 0.8mm +/-0.15mm  |
| T         | 0.8mm +/-0.15mm  |
| S         | 0.58mm MIN       |
| B         | 0.45mm +/-0.15mm |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000                   |

### General Information

|                          |   |
|--------------------------|---|
| Series                   | SMD Auto COG Flex                                 |
| Style                    | SMD Chip  |
| Description              | SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade |
| Features                 | FT-CAP, Ultra-Stable, Automotive Grade            |
| RoHS                     | Yes   |
| Termination              | Flexible Termination                              |
| Marking                  | No  |
| Qualifications           | AEC-Q200  |
| AEC-Q200                 | Yes   |
| Typical Component Weight | 4.6 mg  |
| Shelf Life               | 78 Weeks  |
| MSL                      | 1   |

### Specifications

|  |                           |
|--|---------------------------|
| Capacitance  | 16 pF                     |
| Measurement Condition  | 1 MHz 1.0Vrms             |
| Capacitance Tolerance  | 5%                        |
| Voltage DC   | 50 VDC                    |
| Dielectric Withstanding Voltage                                    | 125 VDC                   |
| Temperature Range  | -55/+125°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade Hour       |
| Insulation Resistance  | 100 GOhms                 |